MA2SD100G

Silicon epitaxial planar type

For super high speed switching

■ Features

- Forward current (Average) $I_{F(AV)} = 200 \text{ mA}$ rectification is possible
- Low forward voltage V_F
- High-density mounting is possible

■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse voltage	V _{RRM}	20	V
Forward current (Average)	I _{F(AV)}	200	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Package

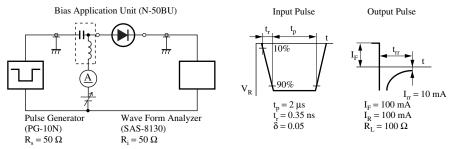
- Code
 - SSMini2-F4
- Pin Name
 - 1: Anode
- 2: Cathode

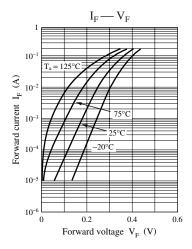
■ Marking Symbol: 2L

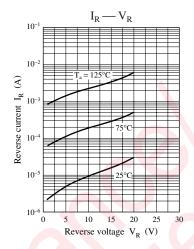
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

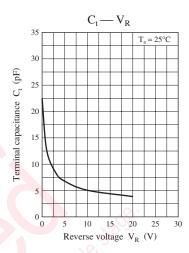
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 5 \text{ mA}$	~0))r	M	0.27	V
	V_{F2}	$I_F = 100 \text{ mA}$			0.40	
	V_{F3}	$I_F = 200 \text{ mA}$	10 N		0.47	
Reverse current	I_R	$V_R = 10 \text{ V}$	7.7		20	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		25		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		3		ns
		I_{rr} = 10 mA, R_L = 100 Ω				

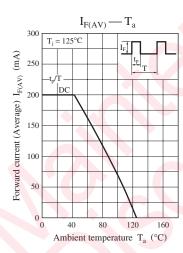
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 250 MHz.
 - 4. *: t_{rr} measurement circuit





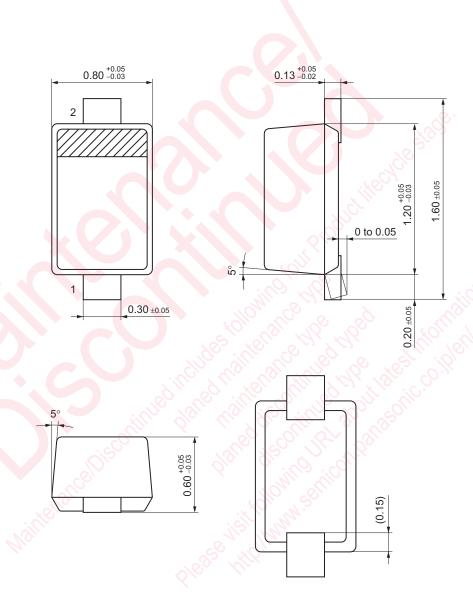






2 SKH00176AED

SSMini2-F4 Unit: mm



SKH00176AED 3

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